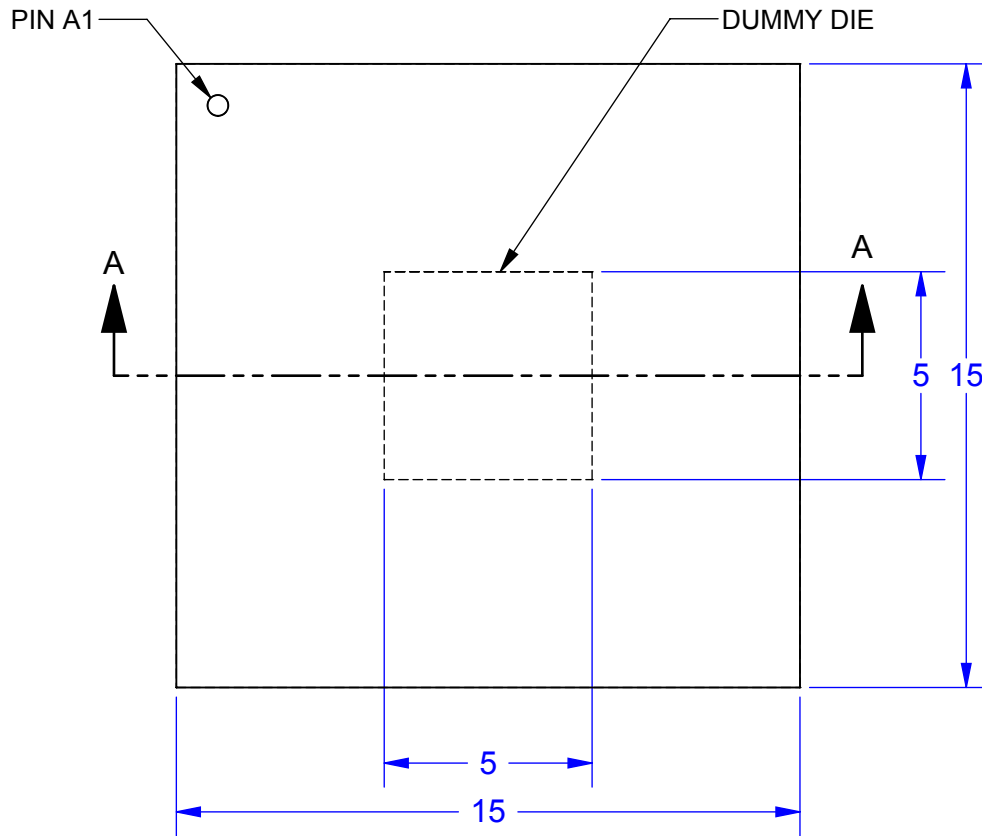
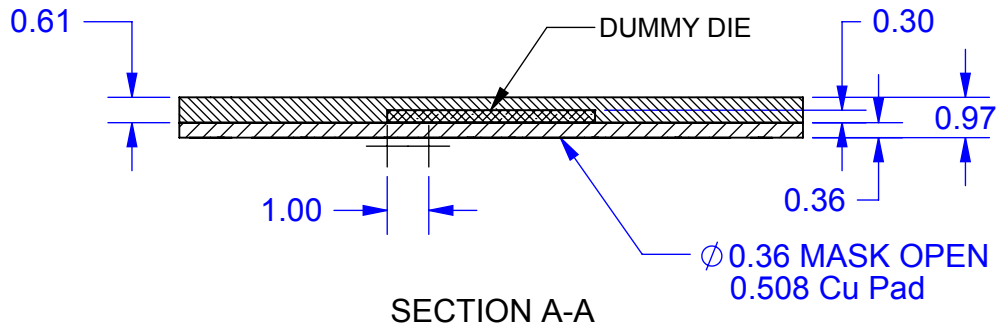
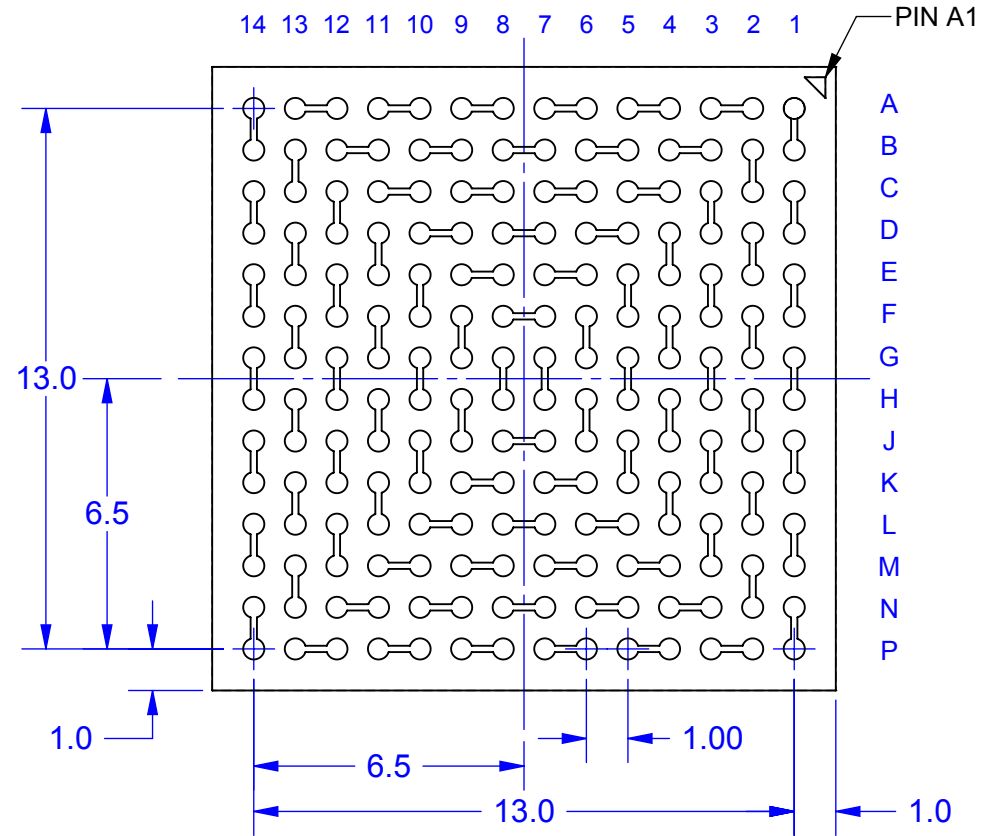


### TOP VIEW



### BALL VIEW



Notes: (Unless Otherwise Specified).

- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER MASK DEFINED PAD OPENING: 0.36mm [14 MIL].
- 3) PAD Cu DIAMETER: 0.508mm [20 MIL].
- 4) SUBSTRATE MATERIAL: BT.
- 5) DUMMY DIE IS OPTIONAL.
- 6) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

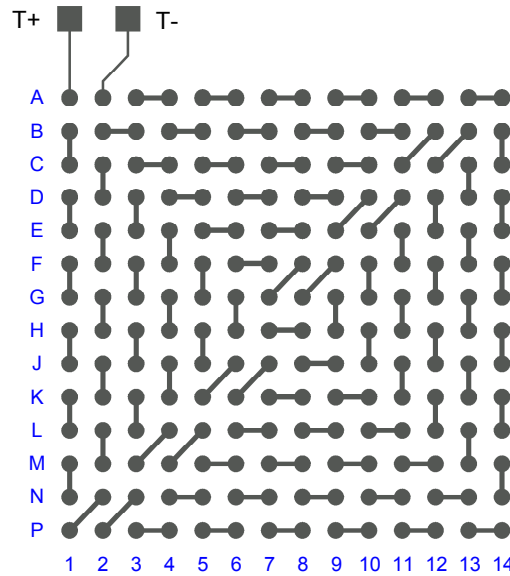
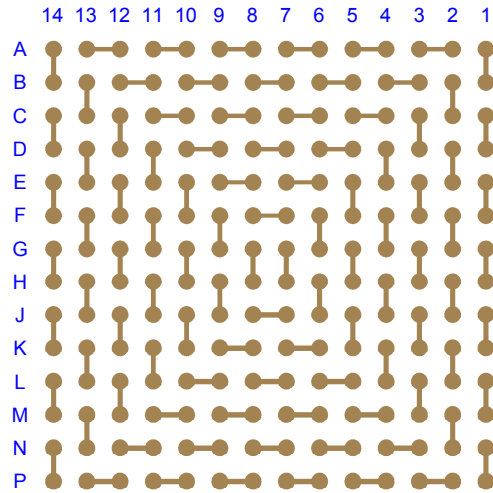
SECTION A-A

#### PART NUMBER TABLE

PART NUMBER	PAD PLATING	BALL CODE	RoHS	Si DIE
LGA196T1.0G-DC149BD	Ni-Au	NONE	YES	YES

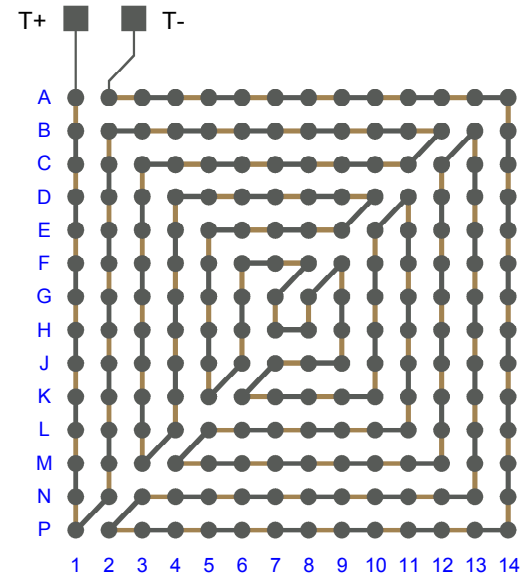
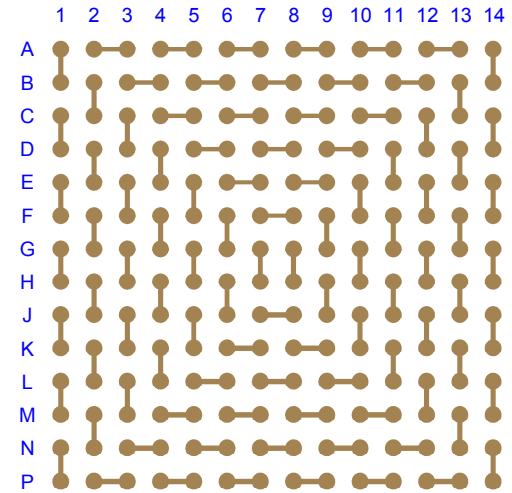
APPROVALS	DATE	<b>TopLine®</b>			
DRAWN T.Au	02/14/14				
ENG M. Hart	02/14/14	TITLE LGA196T1.0G-DC149BD DAISY CHAIN DUMMY			
MFG		SCALE	SIZE	DRAWING NO.	REV
QA		5.5:1	A	511498	A
CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
REVISED					

## BALL VIEW



## TEST VEHICLE BOARD

## BOTTOM SIDE (TOP X-RAY VIEW)



## AFTER MOUNTING

### Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.36mm [14 MIL].

**TopLine**<sup>®</sup>

TITLE LGA196T1.0G-DC149BD  
DAISY CHAIN DUMMY

SCALE 2.4:1	SIZE A	DRAWING NO. 511498	REV A
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DO NOT SCALE DRAWING

SHEET 1 OF 2